

AMENDMENTS

IN THE SPECIFICATION:

Please replace paragraph 19 with the following paragraph.

[0019] In a further preferred refinement of the invention, the submount can be mounted on a main circuit board, in particular by mounting the submount on the main circuit board as a surface mount device (SMD)~~SMD mounting~~. The main circuit board is in this case preferably used as a heat sink for the submount and for the electrical modules arranged on it. For this purpose, the submount preferably has plated holes which, in addition to electrical connection, also provide heat conduction between the electrical components on the submount and the main circuit board. Solder pad contacts are provided in particular on the lower face of the submount, via which the submount is mounted by SMD mounting on the main circuit board.